

WHAT IS CLAIMED IS:

1. A circuit device comprising:  
a substrate;  
5 a semiconductor chip mounted on the substrate; and  
a sealing layer for sealing the semiconductor chip so as  
to cover it, wherein  
the sealing layer comprises a silicone-based material.
- 10 2. A circuit device according to Claim 1, wherein the  
thixotropic index of the silicone-based material is from 2 to 6.
3. A circuit device according to Claim 1, wherein the  
elastic coefficient of the silicone-based material is from 1 to  
15 50 MPa.
4. A circuit device according to Claim 1, further  
comprising a shielding member arranged on the substrate so as to  
cover the sealing layer on the substrate, wherein the shielding  
20 member and the substrate are soldered to each other.
5. A method for making a circuit device, comprising the  
steps of:  
mounting a semiconductor chip on a substrate; and  
25 forming a sealing layer so as to cover the semiconductor  
chip, wherein  
the sealing layer comprises a silicone-based material.

6. A method for making a circuit device according to Claim 5, wherein the thixotropic index of the silicone-based material is from 2 to 6.

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7. A method for making a circuit device according to Claim 5, wherein the elastic coefficient of the silicone-based material is from 1 to 50 MPa.

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8. A method for making a circuit device according to Claim 5, wherein the circuit device comprises a shielding member arranged on the substrate so as to cover the sealing layer on the substrate, and the method further comprises the step of soldering the shielding member and the substrate to each other.

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